Product / Package Information

Package	LQFP
Body Size (mm)	14 X 14 X 1.4
Lead Count	80
Terminal Finish	100 Sn
MS Number	MS010643B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.33E-01	86.91	869100	66.83	668326
Thermosets	Epoxy & Phenol Resin	Proprietary	6.36E-02	12.78	127800	9.83	98276
Other inorganic materials	Carbon black	1333-86-4	1.54E-03	0.31	3100	0.24	2384
Subtotal			4.98E-01	100.00	1000000	76.90	768986

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.34 E-01	97.50	975000	20.69	206871
Copper & its alloys	Iron	7439-89-6	3.23 E-03	2.35	23500	0.50	4986
Copper & its alloys	Zinc	7440-66-6	1.65 E-04	0.12	1200	0.03	255
Copper & its alloys	Phosphorus	7723-14-0	4.12 E-05	0.03	300	0.01	64
Subtotal			1.37 E-01	100.00	1000000	21.22	212175

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.40 E-04	100.00	1000000	0.07	680

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.37 E-03	100.00	1000000	0.98	9839

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.06 E-03	99.0	990000	0.32	3181
Precious metals	Palladium	7440-05-3	2.08 E-05	1.0	10000	0.003	32
Subtotal			2.08 E-03	99.99	1000000	0.32	3213

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.79 E-03	100.00	1000000	0.43	4309

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.80 E-04	73.54	735400	0.06	587
Other organic materials	Epoxy resin A	TS ref# 10013	3.80 E-05	7.35	73500	0.01	59
Others	Anhydride	TS ref# 10181	3.80 E-05	7.35	73500	0.01	59
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.52 E-05	2.94	29400	0.002	23
Other organic materials	Epoxy resin B	TS ref# 10237	1.52 E-05	2.94	29400	0.002	23
Others	Epoxy resin modifier	TS ref# 10038	1.52 E-05	2.94	29400	0.002	23
Others	Anhydride	TS ref# 10180	1.52 E-05	2.94	29400	0.002	23
Subtotal			5.17 E-04	100.00	1000000	0.08	799

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.47 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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